Renesas Electronics America Inc - R5F2L38AMDFA#V0 Datasheet

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SIO, SSU, UART/USART
Peripherals	LCD, POR, PWM, Voltage Detect, WDT
Number of I/O	68
Program Memory Size	96KB (96K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	10K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 16x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-LQFP
Supplier Device Package	80-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f2l38amdfa-v0

Table 1.8 Product List for R8C/L36M Group Current of Jun 2011

Part No.	Internal ROM Capacity		Internal RAM Capacity	Package Type	Remarks
	Program ROM	Data Flash			
R5F2L367MNFP	48 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064KB-A	N Version
R5F2L367MNFA	48 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064GA-A	
R5F2L368MNFP	64 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064KB-A	
R5F2L368MNFA	64 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064GA-A	
R5F2L36AMNFP	96 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064KB-A	
R5F2L36AMNFA	96 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064GA-A	
R5F2L36CMNFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064KB-A	
R5F2L36CMNFA	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064GA-A	
R5F2L367MDFP	48 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064KB-A	D Version
R5F2L367MDFA	48 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064GA-A	
R5F2L368MDFP	64 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064KB-A	
R5F2L368MDFA	64 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064GA-A	
R5F2L36AMDFP	96 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064KB-A	
R5F2L36AMDFA	96 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064GA-A	
R5F2L36CMDFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064KB-A	
R5F2L36CMDFA	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064GA-A	

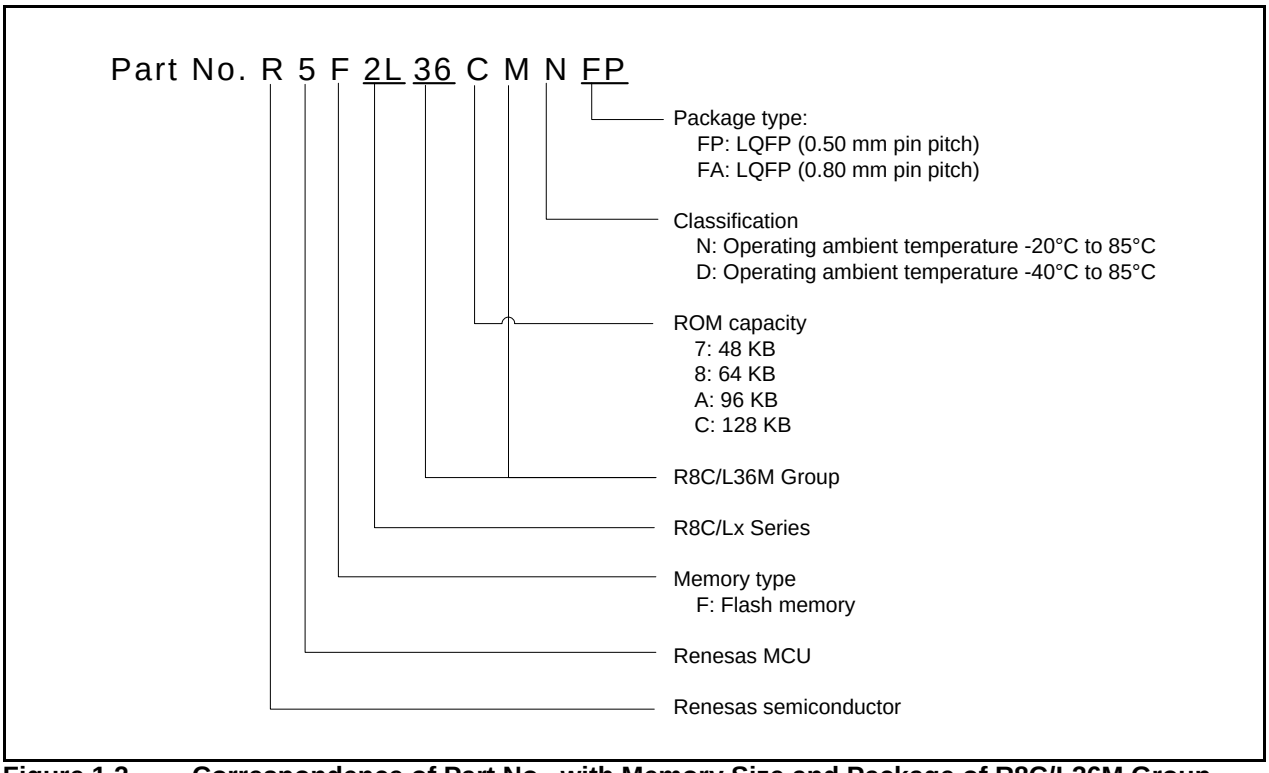
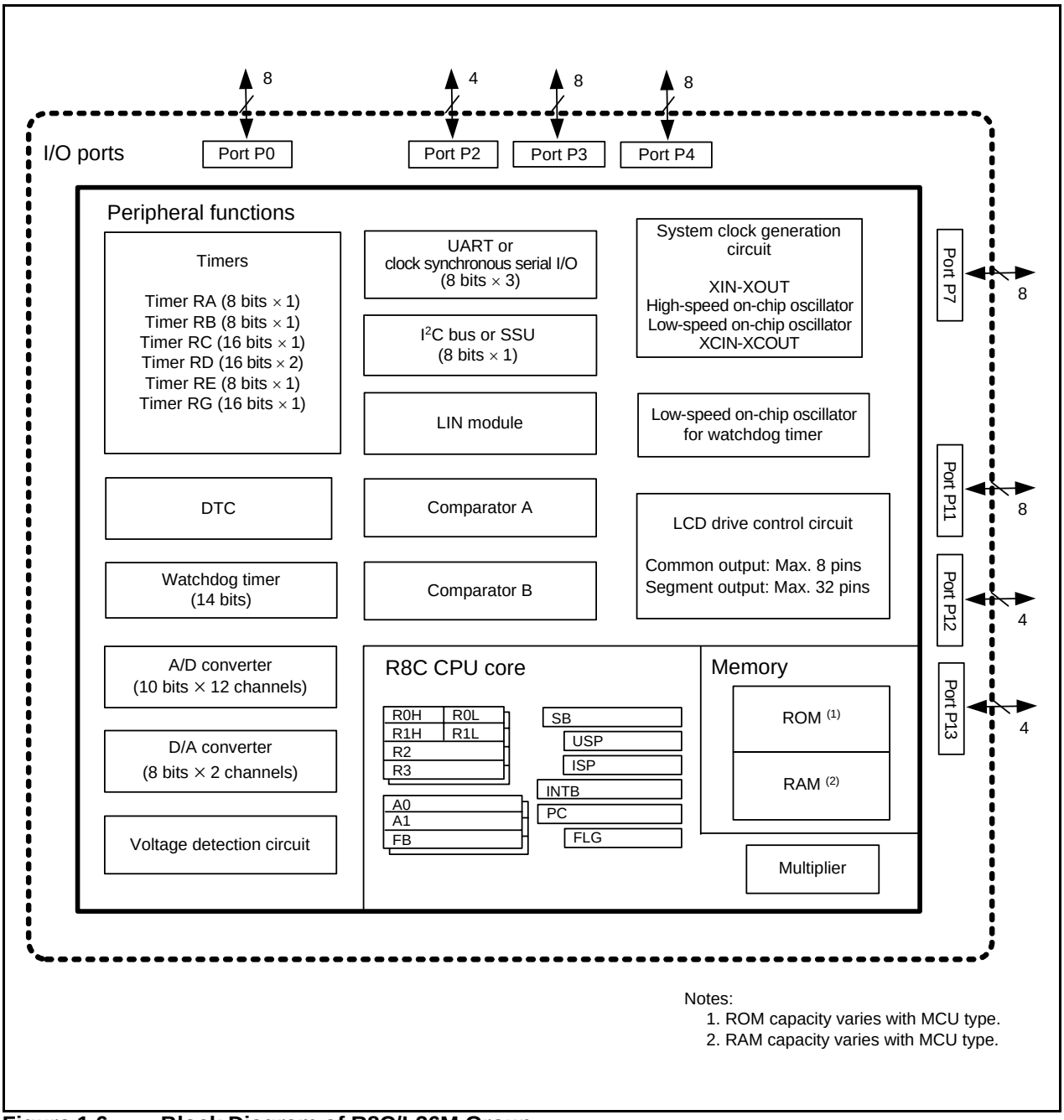
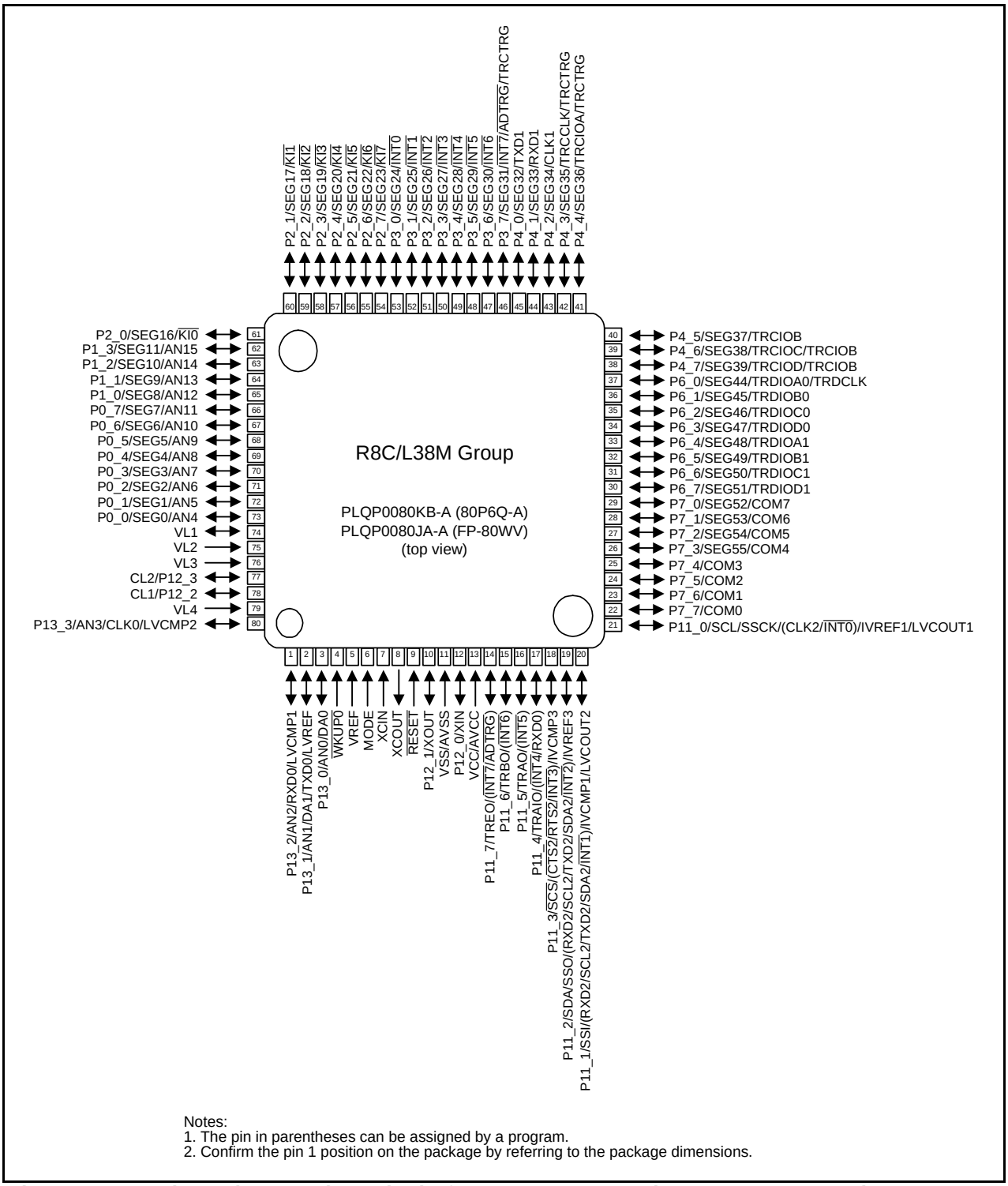


Figure 1.2 Correspondence of Part No., with Memory Size and Package of R8C/L36M Group



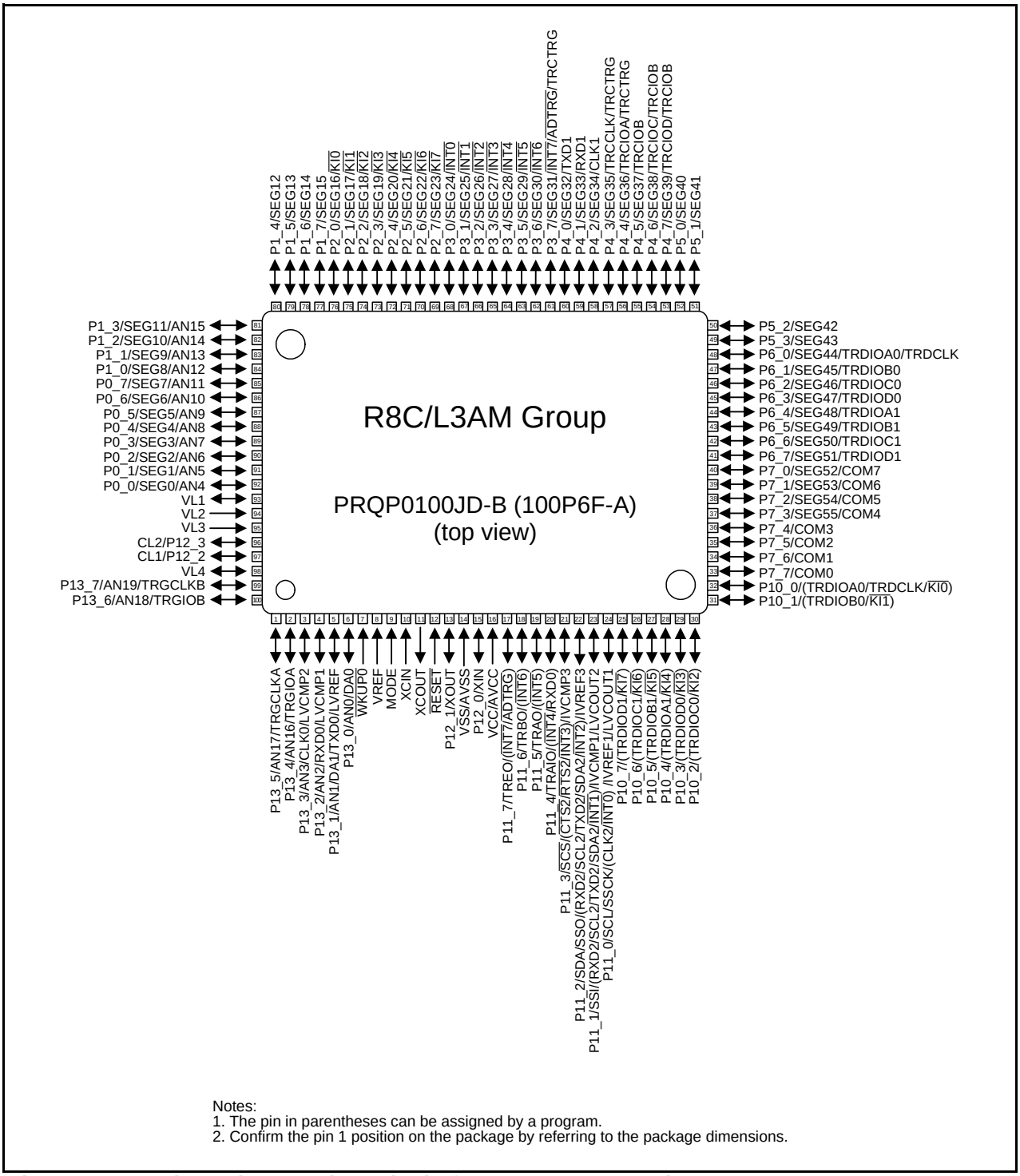
Notes:
1. ROM capacity varies with MCU type.
2. RAM capacity varies with MCU type.

Figure 1.6 Block Diagram of R8C/L36M Group



Notes:
1. The pin in parentheses can be assigned by a program.
2. Confirm the pin 1 position on the package by referring to the package dimensions.

Figure 1.11 Pin Assignment (Top View) of PLQP0080KB-A and PLQP0080JA-A Packages



Notes:
1. The pin in parentheses can be assigned by a program.
2. Confirm the pin 1 position on the package by referring to the package dimensions.

Figure 1.13 Pin Assignment (Top View) of PRQP0100JD-B Package

1.5 Pin Functions

Tables 1.14 and 1.15 list Pin Functions for R8C/L3AM Group.

Table 1.14 Pin Functions for R8C/L3AM Group (1)

Item	Pin Name	I/O Type	Description
Power supply input	VCC, VSS	–	Apply 1.8 V to 5.5 V to the VCC pin. Apply 0 V to the VSS pin.
Analog power supply input	AVCC, AVSS	–	Power supply for the A/D converter. Connect a capacitor between AVCC and AVSS.
Reset input	$\overline{\text{RESET}}$	I	Driving this pin low resets the MCU.
MODE	MODE	I	Connect this pin to VCC via a resistor.
Power-off mode exit input	$\overline{\text{WKUP0}}$	I	This pin is provided for input to exit the mode used in power-off mode. Connect to VSS when not using power-off mode.
XIN clock input	XIN	I	These pins are provided for XIN clock generation circuit I/O. Connect a ceramic oscillator or a crystal oscillator between pins XIN and XOUT. (1) To use an external clock, input it to the XIN pin and leave the XOUT pin open.
XIN clock output	XOUT	O	
XCIN clock input	XCIN	I	These pins are provided for XCIN clock generation circuit I/O. Connect a crystal oscillator between pins XCIN and XCOUT. (1) To use an external clock, input it to the XCIN pin and leave the XCOUT pin open.
XCIN clock output	XCOUT	O	
$\overline{\text{INT}}$ interrupt input	$\overline{\text{INT0}}$ to $\overline{\text{INT7}}$	I	$\overline{\text{INT}}$ interrupt input pins.
Key input interrupt	$\overline{\text{KI0}}$ to $\overline{\text{KI7}}$	I	Key input interrupt input pins
Timer RA	TRAIO	I/O	Timer RA I/O pin
	TRAO	O	Timer RA output pin
Timer RB	TRBO	O	Timer RB output pin
Timer RC	TRCCLK	I	External clock input pin
	TRCTRG	I	External trigger input pin
	TRCIOA, TRCIOB, TRCIOC, TRCIOD	I/O	Timer RC I/O pins
Timer RD	TRDIOA0, TRDIOA1, TRDIOB0, TRDIOB1, TRDIOC0, TRDIOC1, TRDIOD0, TRDIOD1	I/O	Timer RD I/O pins
	TRDCLK	I	External clock input pin
Timer RE	TREO	O	Divided clock output pin
Timer RG	TRGCLKA, TRGCLKB	I	Timer RG input pins
	TRGIOA, TRGIOB	I/O	Timer RG I/O pins
Serial interface	CLK0, CLK1, CLK2	I/O	Transfer clock I/O pins
	RXD0, RXD1, RXD2	I	Serial data input pins
	TXD0, TXD1, TXD2	O	Serial data output pins
	$\overline{\text{CTS2}}$	I	Transmission control input pin
	$\overline{\text{RTS2}}$	O	Reception control output pin
	SCL2	I/O	I^2C mode clock I/O pin
	SDA2	I/O	I^2C mode data I/O pin

I: Input O: Output I/O: Input and output

Note:

1. Contact the oscillator manufacturer for oscillation characteristics.

Table 1.15 Pin Functions for R8C/L3AM Group (2)

Item	Pin Name	I/O Type	Description
I^2C bus	SCL	I/O	Clock I/O pin
	SDA	I/O	Data I/O pin
SSU	SSI	I/O	Data I/O pin
	$\overline{SCS}$	I/O	Chip-select signal I/O pin
	SSCK	I/O	Clock I/O pin
	SSO	I/O	Data I/O pin
Reference voltage input	VREF	I	Reference voltage input pin for the A/D converter and the D/A converter
A/D converter	AN0 to AN11	I	A/D converter analog input pins
	$\overline{ADTRG}$	I	A/D external trigger input pin
D/A converter	DA0, DA1	O	D/A converter output pins
Comparator A	LVCMP1, LVCMP2	I	Comparator A analog voltage input pins
	LVREF	I	Comparator A reference voltage input pin
	LVCOUT1, LVCOUT2	O	Comparator A analog output pins
Comparator B	IVCMP1, IVCMP3	I	Comparator B analog voltage input pins
	IVREF1, IVREF3	I	Comparator B reference voltage input pins
Voltage detection circuit	LVCMP2	I	Detection target voltage input pin for voltage detection 2
I/O ports	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0, P5_3, P6_0 to P6_7 P7_0 to P7_7, P10_0 to P10_7, P11_0 to P11_7, P12_0 to P12_3, P13_0 to P13_7	I/O	CMOS I/O ports. Each port has an I/O select direction register, allowing each pin in the port to be directed for input or output individually. Any port set to input can be set to use a pull-up resistor or not by a program. Ports P10_0 to P10_7 and P11_0 to P11_7 can be used as LED drive ports.
Segment output	SEG0 to SEG55	O	LCD segment output pins
Common output	COM0 to COM7	O	LCD common output pins
Voltage multiplier capacity connect pins	CL1, CL2	O	Connect pins for the LCD control voltage multiplier
LCD power supply	VL1	I/O	Apply the voltage: $0 \leq VL1 \leq VL2 \leq VL3 \leq VL4$. VL1 can be used as the reference potential input or output pin when setting the voltage multiplier.
	VL2 to VL4	I	

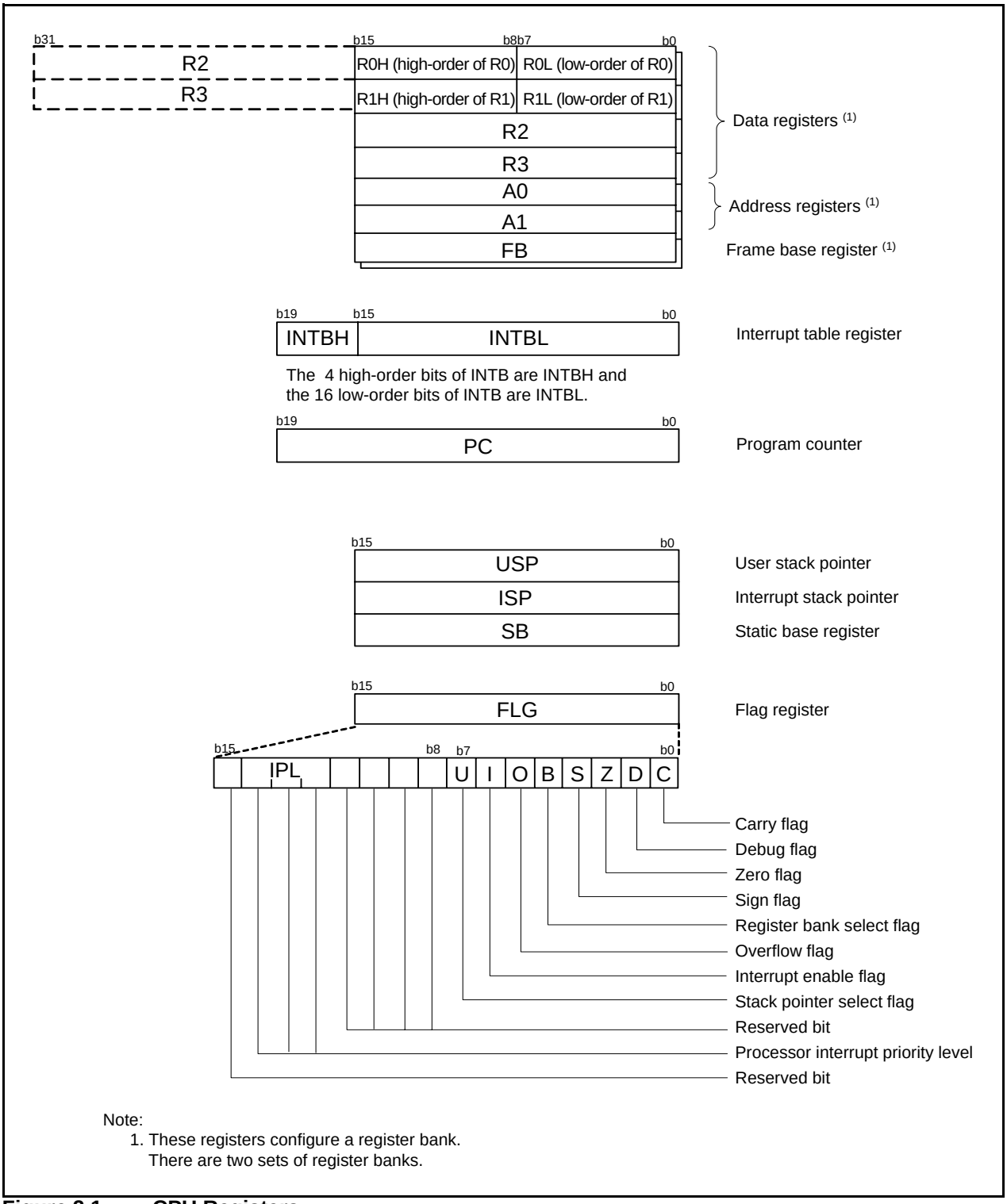
I: Input O: Output I/O: Input and output

Note:

1. Contact the oscillator manufacturer for oscillation characteristics.

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU Registers. The CPU contains 13 registers. R0, R1, R2, R3, A0, A1, and FB configure a register bank. There are two sets of register banks.



Note:
1. These registers configure a register bank.
There are two sets of register banks.

Figure 2.1 CPU Registers

2.8.7 Interrupt Enable Flag (I)

The I flag enables maskable interrupts.
Interrupts are disabled when the I flag is set to 0, and are enabled when the I flag is set to 1. The I flag is set to 0 when an interrupt request is acknowledged.

2.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is set to 0; USP is selected when the U flag is set to 1.
The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL is 3 bits wide and assigns processor interrupt priority levels from level 0 to level 7.
If a requested interrupt has higher priority than IPL, the interrupt is enabled.

2.8.10 Reserved Bit

If necessary, set to 0. When read, the content is undefined.

Table 4.7 SFR Information (7) (1)

Address	Register	Symbol	After Reset
0180h	Timer RA Pin Select Register	TRASR	00h
0181h	Timer RB/RC Pin Select Register	TRBRCSR	00h
0182h	Timer RC Pin Select Register 0	TRCPSR0	00h
0183h	Timer RC Pin Select Register 1	TRCPSR1	00h
0184h	Timer RD Pin Select Register 0	TRDPSR0	00h
0185h	Timer RD Pin Select Register 1	TRDPSR1	00h
0186h			
0187h	Timer RG Pin Select Register	TRGPSR	00h
0188h	UART0 Pin Select Register	U0SR	00h
0189h	UART1 Pin Select Register	U1SR	00h
018Ah	UART2 Pin Select Register 0	U2SR0	00h
018Bh	UART2 Pin Select Register 1	U2SR1	00h
018Ch	SSU/IIC Pin Select Register	SSUIICSR	00h
018Dh	Key Input Pin Select Register	KISR	00h
018Eh	INT Interrupt Input Pin Select Register	INTSR	00h
018Fh	I/O Function Pin Select Register	PINSR	00h
0190h			
0191h			
0192h			
0193h	SS Bit Counter Register	SSBR	11111000b
0194h	SS Transmit Data Register L / IIC bus Transmit Data Register (2)	SSTDR/ICDRT	FFh
0195h	SS Transmit Data Register H (2)	SSTDRH	FFh
0196h	SS Receive Data Register L / IIC bus Receive Data Register (2)	SSRDR/ICDRR	FFh
0197h	SS Receive Data Register H (2)	SSRDRH	FFh
0198h	SS Control Register H / IIC bus Control Register 1 (2)	SSCRH/ICCR1	00h
0199h	SS Control Register L / IIC bus Control Register 2 (2)	SSCRL/ICCR2	01111101b
019Ah	SS Mode Register / IIC bus Mode Register (2)	SSMR/ICMR	00010000b/00011000b
019Bh	SS Enable Register / IIC bus Interrupt Enable Register (2)	SSER/ICIER	00h
019Ch	SS Status Register / IIC bus Status Register (2)	SSSR/ICSR	00h/0000X000b
019Dh	SS Mode Register 2 / Slave Address Register (2)	SSMR2/SAR	00h
019Eh			
019Fh			
01A0h			
01A1h			
01A2h			
01A3h			
01A4h			
01A5h			
01A6h			
01A7h			
01A8h			
01A9h			
01AAh			
01ABh			
01ACh			
01ADh			
01AEh			
01AFh			
01B0h			
01B1h			
01B2h	Flash Memory Status Register	FST	10000X00b
01B3h			
01B4h	Flash Memory Control Register 0	FMR0	00h
01B5h	Flash Memory Control Register 1	FMR1	00h
01B6h	Flash Memory Control Register 2	FMR2	00h
01B7h			
01B8h			
01B9h			
01BAh			
01BBh			
01BCh			
01BDh			
01BEh			
01BFh			

X: Undefined

Notes:

1. Blank spaces are reserved. No access is allowed.
2. Selectable by the IICSEL bit in the SSUIICSR register.

Table 4.9 SFR Information (9) (1)

Address	Register	Symbol	After Reset
0200h	LCD Control Register	LCR0	00h
0201h	LCD Bias Control Register	LCR1	00h
0202h	LCD Display Control Register	LCR2	X0000000b
0203h	LCD Clock Control Register	LCR3	00h
0204h			
0205h			
0206h	LCD Port Select Register 0	LSE0	00h
0207h	LCD Port Select Register 1	LSE1	00h
0208h	LCD Port Select Register 2	LSE2	00h
0209h	LCD Port Select Register 3	LSE3	00h
020Ah	LCD Port Select Register 4	LSE4	00h
020Bh	LCD Port Select Register 5	LSE5	00h
020Ch	LCD Port Select Register 6	LSE6	00h
020Dh	LCD Port Select Register 7	LSE7	00h
020Eh			
020Fh			
0210h	LCD Display Data Register	LRA0L	XXh
0211h		LRA1L	XXh
0212h		LRA2L	XXh
0213h		LRA3L	XXh
0214h		LRA4L	XXh
0215h		LRA5L	XXh
0216h		LRA6L	XXh
0217h		LRA7L	XXh
0218h		LRA8L	XXh
0219h		LRA9L	XXh
021Ah		LRA10L	XXh
021Bh		LRA11L	XXh
021Ch		LRA12L	XXh
021Dh		LRA13L	XXh
021Eh		LRA14L	XXh
021Fh		LRA15L	XXh
0220h		LRA16L	XXh
0221h		LRA17L	XXh
0222h		LRA18L	XXh
0223h		LRA19L	XXh
0224h		LRA20L	XXh
0225h		LRA21L	XXh
0226h		LRA22L	XXh
0227h		LRA23L	XXh
0228h		LRA24L	XXh
0229h		LRA25L	XXh
022Ah		LRA26L	XXh
022Bh		LRA27L	XXh
022Ch		LRA28L	XXh
022Dh		LRA29L	XXh
022Eh		LRA30L	XXh
022Fh		LRA31L	XXh
0230h		LRA32L	XXh
0231h		LRA33L	XXh
0232h		LRA34L	XXh
0233h		LRA35L	XXh
0234h		LRA36L	XXh
0235h		LRA37L	XXh
0236h		LRA38L	XXh
0237h		LRA39L	XXh
0238h		LRA40L	XXh
0239h		LRA41L	XXh
023Ah		LRA42L	XXh
023Bh		LRA43L	XXh
023Ch		LRA44L	XXh
023Dh		LRA45L	XXh
023Eh		LRA46L	XXh
023Fh		LRA47L	XXh

X: Undefined

Note:

1. Blank spaces are reserved. No access is allowed.

Table 4.10 SFR Information (10) (1)

Address	Register	Symbol	After Reset
0240h	LCD Display Data Register	LRA48L	XXh
0241h		LRA49L	XXh
0242h		LRA50L	XXh
0243h		LRA51L	XXh
0244h		LRA52L	XXh
0245h		LRA53L	XXh
0246h		LRA54L	XXh
0247h		LRA55L	XXh
0248h			
0249h			
024Ah			
024Bh			
024Ch			
024Dh			
024Eh			
024Fh			
0250h			
0251h			
0252h			
0253h			
0254h			
0255h			
0256h			
0257h			
0258h			
0259h			
025Ah			
025Bh			
025Ch			
025Dh			
025Eh			
025Fh			
0260h			
0261h			
0262h			
0263h			
0264h			
0265h			
0266h			
0267h			
0268h			
0269h			
026Ah			
026Bh			
026Ch			
026Dh			
026Eh			
026Fh			
0270h	LCD Display Control Data Register	LRA0H	XXh
0271h		LRA1H	XXh
0272h		LRA2H	XXh
0273h		LRA3H	XXh
0274h		LRA4H	XXh
0275h		LRA5H	XXh
0276h		LRA6H	XXh
0277h		LRA7H	XXh
0278h		LRA8H	XXh
0279h		LRA9H	XXh
027Ah		LRA10H	XXh
027Bh		LRA11H	XXh
027Ch		LRA12H	XXh
027Dh		LRA13H	XXh
027Eh		LRA14H	XXh
027Fh		LRA15H	XXh

X: Undefined
Note:
1. Blank spaces are reserved. No access is allowed.

Table 4.14 SFR Information (14) (1)

Address	Register	Symbol	After Reset
2C70h	DTC Control Data 6	DTCD6	XXh
2C71h			XXh
2C72h			XXh
2C73h			XXh
2C74h			XXh
2C75h			XXh
2C76h			XXh
2C77h			XXh
2C78h	DTC Control Data 7	DTCD7	XXh
2C79h			XXh
2C7Ah			XXh
2C7Bh			XXh
2C7Ch			XXh
2C7Dh			XXh
2C7Eh			XXh
2C7Fh			XXh
2C80h	DTC Control Data 8	DTCD8	XXh
2C81h			XXh
2C82h			XXh
2C83h			XXh
2C84h			XXh
2C85h			XXh
2C86h			XXh
2C87h			XXh
2C88h	DTC Control Data 9	DTCD9	XXh
2C89h			XXh
2C8Ah			XXh
2C8Bh			XXh
2C8Ch			XXh
2C8Dh			XXh
2C8Eh			XXh
2C8Fh			XXh
2C90h	DTC Control Data 10	DTCD10	XXh
2C91h			XXh
2C92h			XXh
2C93h			XXh
2C94h			XXh
2C95h			XXh
2C96h			XXh
2C97h			XXh
2C98h	DTC Control Data 11	DTCD11	XXh
2C99h			XXh
2C9Ah			XXh
2C9Bh			XXh
2C9Ch			XXh
2C9Dh			XXh
2C9Eh			XXh
2C9Fh			XXh
2CA0h	DTC Control Data 12	DTCD12	XXh
2CA1h			XXh
2CA2h			XXh
2CA3h			XXh
2CA4h			XXh
2CA5h			XXh
2CA6h			XXh
2CA7h			XXh
2CA8h	DTC Control Data 13	DTCD13	XXh
2CA9h			XXh
2CAAh			XXh
2CABh			XXh
2CACh			XXh
2CADh			XXh
2CAEh			XXh
2CAFh			XXh

X: Undefined
Note:
1. Blank spaces are reserved. No access is allowed.

5.2 Recommended Operating Conditions

Table 5.2 Recommended Operating Conditions
(Vcc = 1.8 to 5.5 V and Topr = −20 to 85°C (N version) / −40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter				Conditions	Standard			Unit
						Min.	Typ.	Max.	
Vcc/AVcc	Supply voltage					1.8	—	5.5	V
Vss/AVss	Supply voltage					—	0	—	V
VIH	Input “H” voltage	Other than CMOS input			4.0 V ≤ Vcc ≤ 5.5 V	0.8 Vcc	—	Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0.8 Vcc	—	Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0.9 Vcc	—	Vcc	V
		CMOS input	Input level switching function (I/O port)	Input level selection : 0.35 Vcc	4.0 V ≤ Vcc ≤ 5.5 V	0.5 Vcc	—	Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0.55 Vcc	—	Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0.65 Vcc	—	Vcc	V
				Input level selection : 0.5 Vcc	4.0 V ≤ Vcc ≤ 5.5 V	0.65 Vcc	—	Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0.7 Vcc	—	Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0.8 Vcc	—	Vcc	V
				Input level selection : 0.7 Vcc	4.0 V ≤ Vcc ≤ 5.5 V	0.85 Vcc	—	Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0.85 Vcc	—	Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0.85 Vcc	—	Vcc	V
VIL	Input “L” voltage	Other than CMOS input			4.0 V ≤ Vcc ≤ 5.5 V	0	—	0.2 Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0	—	0.2 Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0	—	0.05 Vcc	V
		CMOS input	Input level switching function (I/O port)	Input level selection : 0.35 Vcc	4.0 V ≤ Vcc ≤ 5.5 V	0	—	0.2 Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0	—	0.2 Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0	—	0.2 Vcc	V
				Input level selection : 0.5 Vcc	4.0 V ≤ Vcc ≤ 5.5 V	0	—	0.4 Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0	—	0.3 Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0	—	0.2 Vcc	V
				Input level selection : 0.7 Vcc	4.0 V ≤ Vcc ≤ 5.5 V	0	—	0.55 Vcc	V
					2.7 V ≤ Vcc < 4.0 V	0	—	0.45 Vcc	V
					1.8 V ≤ Vcc < 2.7 V	0	—	0.35 Vcc	V
IOH(sum)	Peak sum output “H” current	Sum of all pins IOH(peak)				—	—	−160	mA
IOH(sum)	Average sum output “H” current	Sum of all pins IOH(avg)				—	—	−80	mA
IOH(peak)	Peak output “H” current	Port P10, P11 (2)				—	—	−40	mA
		Other pins				—	—	−10	mA
IOH(avg)	Average output “H” current (1)	Port P10, P11 (2)				—	—	−20	mA
		Other pins				—	—	−5	mA
IOL(sum)	Peak sum output “L” current	Sum of all pins IOL(peak)				—	—	160	mA
IOL(sum)	Average sum output “L” current	Sum of all pins IOL(avg)				—	—	80	mA
IOL(peak)	Peak output “L” current	Port P10, P11 (2)				—	—	40	mA
		Other pins				—	—	10	mA
IOL(avg)	Average output “L” current (1)	Port P10, P11 (2)				—	—	20	mA
		Other pins				—	—	5	mA
f(XIN)	XIN clock input oscillation frequency				2.7 V ≤ Vcc ≤ 5.5 V	—	—	20	MHz
					1.8 V ≤ Vcc < 2.7 V	—	—	5	MHz
f(XCIN)	XCIN clock input oscillation frequency				1.8 V ≤ Vcc ≤ 5.5 V	—	32.768	50	kHz
fOCO40M	When used as the count source for timer RC, timer RD, or timer RG (3)				2.7 V ≤ Vcc ≤ 5.5 V	32	—	40	MHz
fOCO-F	fOCO-F frequency				2.7 V ≤ Vcc ≤ 5.5 V	—	—	20	MHz
					1.8 V ≤ Vcc < 2.7 V	—	—	5	MHz
—	System clock frequency				2.7 V ≤ Vcc ≤ 5.5 V	—	—	20	MHz
					1.8 V ≤ Vcc < 2.7 V	—	—	5	MHz
f(BCLK)	CPU clock frequency				2.7 V ≤ Vcc ≤ 5.5 V	—	—	20	MHz
					1.8 V ≤ Vcc < 2.7 V	—	—	5	MHz

Notes:
1. The average output current indicates the average value of current measured during 100 ms.
2. This applies when the drive capacity of the output transistor is set to High by registers P10DRR and P11DRR. When the drive capacity is set to Low, the value of any other pin applies.
3. fOCO40M can be used as the count source for timer RC, timer RD, or timer RG in the range of Vcc = 2.7 V to 5.5V.

Table 5.4 D/A Converter Characteristics
(VCC/AVCC = Vref = 2.7 to 5.5 V and Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Resolution		—	—	8	Bit
—	Absolute accuracy		—	—	2.5	LSB
tsu	Setup time		—	—	3	µs
RO	Output resistor		—	6	—	kΩ
IVref	Reference power input current	(Note 1)	—	—	1.5	mA

Note:
1. This applies when one D/A converter is used and the value of the DAi register (i = 0 or 1) for the unused D/A converter is 00h. The resistor ladder of the A/D converter is not included.

Table 5.5 Comparator A Characteristics
(VCC = 2.7 to 5.5 V and Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
LVREF	External reference voltage input range		1.4	–	VCC	V
LVCMP1, LVCMP2	External comparison voltage input range		–0.3	–	VCC + 0.3	V
–	Offset		–	50	200	mV
–	Comparator output delay time (1)	At falling, VI = Vref – 100 mV	–	3	–	µs
		At falling, VI = Vref – 1 V or below	–	1.5	–	µs
		At rising, VI = Vref + 100 mV	–	2	–	µs
		At rising, VI = Vref + 1 V or above	–	0.5	–	µs
–	Comparator operating current	VCC = 5.0 V	–	0.5	–	µA

Note:
1. When the digital filter is disabled.

Table 5.6 Comparator B Characteristics
(VCC = 2.7 to 5.5 V and Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
Vref	IVREF1, IVREF3 input reference voltage		0	—	VCC – 1.4	V
VI	IVCMP1, IVCMP3 input voltage		–0.3	—	VCC + 0.3	V
—	Offset		—	5	100	mV
td	Comparator output delay time (1)	VI = Vref ± 100 mV	—	0.1	—	µs
ICMP	Comparator operating current	VCC = 5.0 V	—	17.5	—	µA

Note:
1. When the digital filter is disabled.

Table 5.7 Flash Memory (Program ROM) Characteristics
(V_{CC} = 2.7 to 5.5 V and T_{opr} = 0 to 60°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Program/erase endurance (1)		1,000 (2)	—	—	times
—	Byte program time		—	80	500	µs
—	Word program time		—	120	750	µs
—	Block erase time		—	0.3	—	s
$t_{d(SR-SUS)}$	Time delay from suspend request until suspend		—	—	5 + CPU clock × 3 cycles	ms
—	Interval from erase start/restart until following suspend request		0	—	—	ms
—	Time from suspend until erase restart		—	—	30+CPU clock × 1 cycle	µs
$t_{d(CMDRST-READY)}$	Time from when command is forcibly terminated until reading is enabled		—	—	30+CPU clock × 1 cycle	µs
—	Program, erase voltage		2.7	—	5.5	V
—	Read voltage		1.8	—	5.5	V
—	Program, erase temperature		0	—	60	°C
—	Data hold time (6)	Ambient temperature = 55°C	20	—	—	year

Notes:
1. Definition of programming/erasure endurance
   The programming and erasure endurance is defined on a per-block basis.
   If the programming and erasure endurance is n (n = 1,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
   However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
2. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
3. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
4. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
5. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
6. The data hold time includes time that the power supply is off or the clock is not supplied.

Table 5.20 DC Characteristics (3) [2.7 V ≤ Vcc < 4.0 V]
(Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter		Condition	Standard			Unit
				Min.	Typ.	Max.	
V_{OH}	Output “H” voltage	Port P10, P11 (1)	I_{OH} = –5 mA	V_{CC} – 0.5	—	V_{CC}	V
		Other pins	I_{OH} = –1 mA	V_{CC} – 0.5	—	V_{CC}	V
		XOUT	I_{OH} = –200 μA	1.0	—	—	V
V_{OL}	Output “L” voltage	Port P10, P11 (1)	I_{OL} = 5 mA	—	—	0.5	V
		Other pins	I_{OL} = 1 mA	—	—	0.5	V
		XOUT	I_{OL} = 200 μA	—	—	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$, $\overline{INT1}$, $\overline{INT2}$, $\overline{INT3}$, $\overline{INT4}$, $\overline{INT5}$, $\overline{INT6}$, $\overline{INT7}$, $\overline{KI0}$, $\overline{KI1}$, $\overline{KI2}$, $\overline{KI3}$, $\overline{KI4}$, $\overline{KI5}$, $\overline{KI6}$, $\overline{KI7}$, TRAIO, TRCIOA, TRCIOB, TRCIOC, TRCIOD, TRDIOA0, TRDIOB0, TRDIOC0, TRDIOD0, TRDIOA1, TRDIOB1, TRDIOC1, TRDIOD1, TRCTRG, TRCCLK, TRGCLKA, TRGCLKB, $\overline{TRGIOA}$, TRGIOB, $\overline{ADTRG}$, RXD0, RXD1, RXD2, CLK0, CLK1, CLK2, SSI, SCL, SDA, SSO		0.05	0.4	—	V
		$\overline{RESET}$, $\overline{WKUP0}$		0.1	0.8	—	V
I_{IH}	Input “H” current		VI = 3.0 V, V_{CC} = 3.0 V	—	—	5.0	μA
I_{IL}	Input “L” current		VI = 0 V, V_{CC} = 3.0 V	—	—	–5.0	μA
R_{PULLUP}	Pull-up resistance		VI = 0 V, V_{CC} = 3.0 V	30	100	170	kΩ
R_{fXIN}	Feedback resistance	XIN		—	0.3	—	MΩ
R_{fXCIN}	Feedback resistance	XCIN		—	14	—	MΩ
V_{RAM}	RAM hold voltage		During stop mode	1.8	—	—	V

Note:
1. This applies when the drive capacity of the output transistor is set to High by registers P10DRR and P11DRR. When the drive capacity is set to Low, the value of any other pin applies.

Table 5.21 DC Characteristics (4) [2.7 V ≤ Vcc < 4.0 V]
(Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter		Condition							Standard			Unit
			Oscillation Circuit		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other	Min.	Typ. (3)	Max.	
			XIN (2)	XCIN	High-Speed (fOCO-F)	Low-Speed							
Icc	Power supply current (1)	High-speed clock mode	20 MHz	Off	Off	125 kHz	No division	—		—	7.0	14.5	mA
			10 MHz	Off	Off	125 kHz	No division	—		—	3.6	10	mA
			20 MHz	Off	Off	125 kHz	Divide-by-8	—		—	3.0	—	mA
			10 MHz	Off	Off	125 kHz	Divide-by-8	—		—	1.5	—	mA
		High-speed on-chip oscillator mode	Off	Off	20 MHz	125 kHz	No division	—		—	7.0	14.5	mA
			Off	Off	20 MHz	125 kHz	Divide-by-8	—		—	3.0	—	mA
			Off	Off	10 MHz	125 kHz	No division	—		—	4.0	—	mA
			Off	Off	10 MHz	125 kHz	Divide-by-8	—		—	1.7	—	mA
			Off	Off	4 MHz	125 kHz	Divide-by-16	MSTIIC = 1 MSTTRD = 1 MSTTRC = 1 MSTTRG = 1		—	1	—	mA
		Low-speed on-chip oscillator mode	Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 VCA20 = 0		—	85	390	µA
		Low-speed clock mode	Off	32 kHz	Off	Off	No division	FMR27 = 1 VCA20 = 0		—	90	400	µA
			Off	32 kHz	Off	Off	No division	FMSTP = 1 VCA20 = 0	Flash memory off Program operation on RAM	—	50	—	µA
		Wait mode	Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1	While a WAIT instruction is executed Peripheral clock operation	—	15	90	µA
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 1	While a WAIT instruction is executed Peripheral clock off	—	5	80	µA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 0	While a WAIT instruction is executed Peripheral clock off Timer RE operation in real-time clock mode	LCD drive control circuit (4) When external division resistors are used	—	5	—	µA
										LCD drive control circuit (5) When the internal voltage multiplier is used	—	11	—	µA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 1	While a WAIT instruction is executed Peripheral clock off Timer RE operation in real-time clock mode		—	3.5	—	µA
		Stop mode	Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 25°C Peripheral clock off		—	2	5.0	µA
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 85°C Peripheral clock off		—	13.0	—	µA
		Power-off mode	Off	Off	Off	Off	—	—	Power-off 0 Topr = 25°C		—	0.02	0.2	µA
			Off	Off	Off	Off	—	—	Power-off 0 Topr = 85°C		—	0.3	—	µA
			Off	32 kHz	Off	Off	—	—	Power-off 1 Topr = 25°C		—	1.4	2.8	µA
			Off	32 kHz	Off	Off	—	—	Power-off 1 Topr = 85°C		—	1.8	—	µA

Notes:
1. Vcc = 2.7 V to 4.0 V, single chip mode, output pins are open, and other pins are Vss.
2. XIN is set to square wave input.
3. Vcc = 3.0 V
4. VLCD = Vcc, external division resistors are used for VL4 to VL1, 1/3 bias, 1/4 duty, f(FR) = 64 Hz, SEG0 to SEG55 are selected, and segment and common output pins are open. The standard value does not include the current that flows through external division resistors.
5. The internal voltage multiplier is used, bits LVLS3 to LVLS0 in the LCR1 register = 1011b, 1/3 bias, 1/4 duty, f(FR) = 64 Hz, SEG0 to SEG55 are selected, and segment and common output pins are open.

Table 5.23 DC Characteristics (6) [1.8 V ≤ Vcc < 2.7 V]
(Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter		Condition							Standard			Unit
			Oscillation Circuit		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other	Min.	Typ. (3)	Max.	
			XIN (2)	XCIN	High-Speed (fOCO-F)	Low-Speed							
Icc	Power supply current (1)	High-speed clock mode	5 MHz	Off	Off	125 kHz	No division	—		—	2.2	—	mA
			5 MHz	Off	Off	125 kHz	Divide-by-8	—		—	0.8	—	mA
		High-speed on-chip oscillator mode	Off	Off	5 MHz	125 kHz	No division	—		—	2.5	10	mA
			Off	Off	5 MHz	125 kHz	Divide-by-8	—		—	1.7	—	mA
			Off	Off	4 MHz	125 kHz	Divide-by-16	MSTIIC = 1 MSTTRD = 1 MSTTRC = 1 MSTTRG = 1		—	1	—	mA
		Low-speed on-chip oscillator mode	Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 VCA20 = 0		—	90	300	µA
		Low-speed clock mode	Off	32 kHz	Off	Off	No division	FMR27 = 1 VCA20 = 0		—	90	400	µA
			Off	32 kHz	Off	Off	No division	FMSTP = 1 VCA20 = 0	Flash memory off Program operation on RAM	—	45	—	µA
		Wait mode	Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1	While a WAIT instruction is executed Peripheral clock operation	—	15	90	µA
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 1	While a WAIT instruction is executed Peripheral clock off	—	4	80	µA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 0	While a WAIT instruction is executed Peripheral clock off Timer RE operation in real-time clock mode	LCD drive control circuit (4) When external division resistors are used	—	4	—	µA
										LCD drive control circuit (5) When the internal voltage multiplier is used	—	11	—	µA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 VCA20 = 1 CM02 = 1 CM01 = 1	While a WAIT instruction is executed Peripheral clock off Timer RE operation in real-time clock mode		—	3.5	—	µA
		Stop mode	Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 25°C Peripheral clock off		—	2.0	5.0	µA
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 85°C Peripheral clock off		—	13	—	µA
		Power-off mode	Off	Off	Off	Off	—	—	Power-off 0 Topr = 25°C		—	0.02	0.2	µA
			Off	Off	Off	Off	—	—	Power-off 0 Topr = 85°C		—	0.3	—	µA
			Off	32 kHz	Off	Off	—	—	Power-off 1 Topr = 25°C		—	1.3	2.6	µA
			Off	32 kHz	Off	Off	—	—	Power-off 1 Topr = 85°C		—	1.7	—	µA

Notes:
1. Vcc = 1.8 V to 2.7 V, single chip mode, output pins are open, and other pins are Vss.
2. XIN is set to square wave input.
3. Vcc = 2.2 V
4. VLCD = Vcc, external division resistors are used for VL4 to VL1, 1/3 bias, 1/4 duty, f(FR) = 64 Hz, SEG0 to SEG55 are selected, and segment and common output pins are open.The standard value does not include the current that flows through external division resistors.
5. The internal voltage multiplier is used, bits LVLS3 to LVLS0 in the LCR1 register = 1011b, 1/3 bias, 1/4 duty, f(FR) = 64 Hz, SEG0 to SEG55 are selected, and segment and common output pins are open.

General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this manual, refer to the relevant sections of the manual. If the descriptions under General Precautions in the Handling of MPU/MCU Products and in the body of the manual differ from each other, the description in the body of the manual takes precedence.

1. Handling of Unused Pins

   Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

   — The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   — The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.

   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   — The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   — When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to one with a different part number, confirm that the change will not lead to problems.

   — The characteristics of MPU/MCU in the same group but having different part numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different part numbers, implement a system-evaluation test for each of the products.

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Renesas Electronics America Inc.
2880 Scott Boulevard Santa Clara, CA 95050-2554, U.S.A.
Tel: +1-408-588-6000, Fax: +1-408-588-6130

Renesas Electronics Canada Limited
1101 Nicholson Road, Newmarket, Ontario L3Y 9C3, Canada
Tel: +1-905-898-5441, Fax: +1-905-898-3220

Renesas Electronics Europe Limited
Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K
Tel: +44-1628-585-100, Fax: +44-1628-585-900

Renesas Electronics Europe GmbH
Arcadiastrasse 10, 40472 Düsseldorf, Germany
Tel: +49-211-65030, Fax: +49-211-6503-1327

Renesas Electronics (China) Co., Ltd.
7th Floor, Quantum Plaza, No.27 ZhiChunLu Haidian District, Beijing 100083, P.R.China
Tel: +86-10-8235-1155, Fax: +86-10-8235-7679

Renesas Electronics (Shanghai) Co., Ltd.
Unit 204, 205, AZIA Center, No.1233 Lujiazui Ring Rd., Pudong District, Shanghai 200120, China
Tel: +86-21-5877-1818, Fax: +86-21-6887-7858 / -7898

Renesas Electronics Hong Kong Limited
Unit 1601-1613, 16/F., Tower 2, Grand Century Place, 193 Prince Edward Road West, Mongkok, Kowloon, Hong Kong
Tel: +852-2886-9318, Fax: +852 2886-9022/9044

Renesas Electronics Taiwan Co., Ltd.
13F, No. 363, Fu Shing North Road, Taipei, Taiwan
Tel: +886-2-8175-9600, Fax: +886 2-8175-9670

Renesas Electronics Singapore Pte. Ltd.
1 harbourFront Avenue, #06-10, keppel Bay Tower, Singapore 098632
Tel: +65-6213-0200, Fax: +65-6278-8001

Renesas Electronics Malaysia Sdn.Bhd.
Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No. 18, Jln Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: +60-3-7955-9390, Fax: +60-3-7955-9510

Renesas Electronics Korea Co., Ltd.
11F., Samik Lavied' or Bldg., 720-2 Yeoksam-Dong, Kangnam-Ku, Seoul 135-080, Korea
Tel: +82-2-558-3737, Fax: +82-2-558-5141

Colophon 1.1